



SHENZHEN HI-LINK ELECTRONIC CO., LTD

HLK-RM08S USER MANUAL

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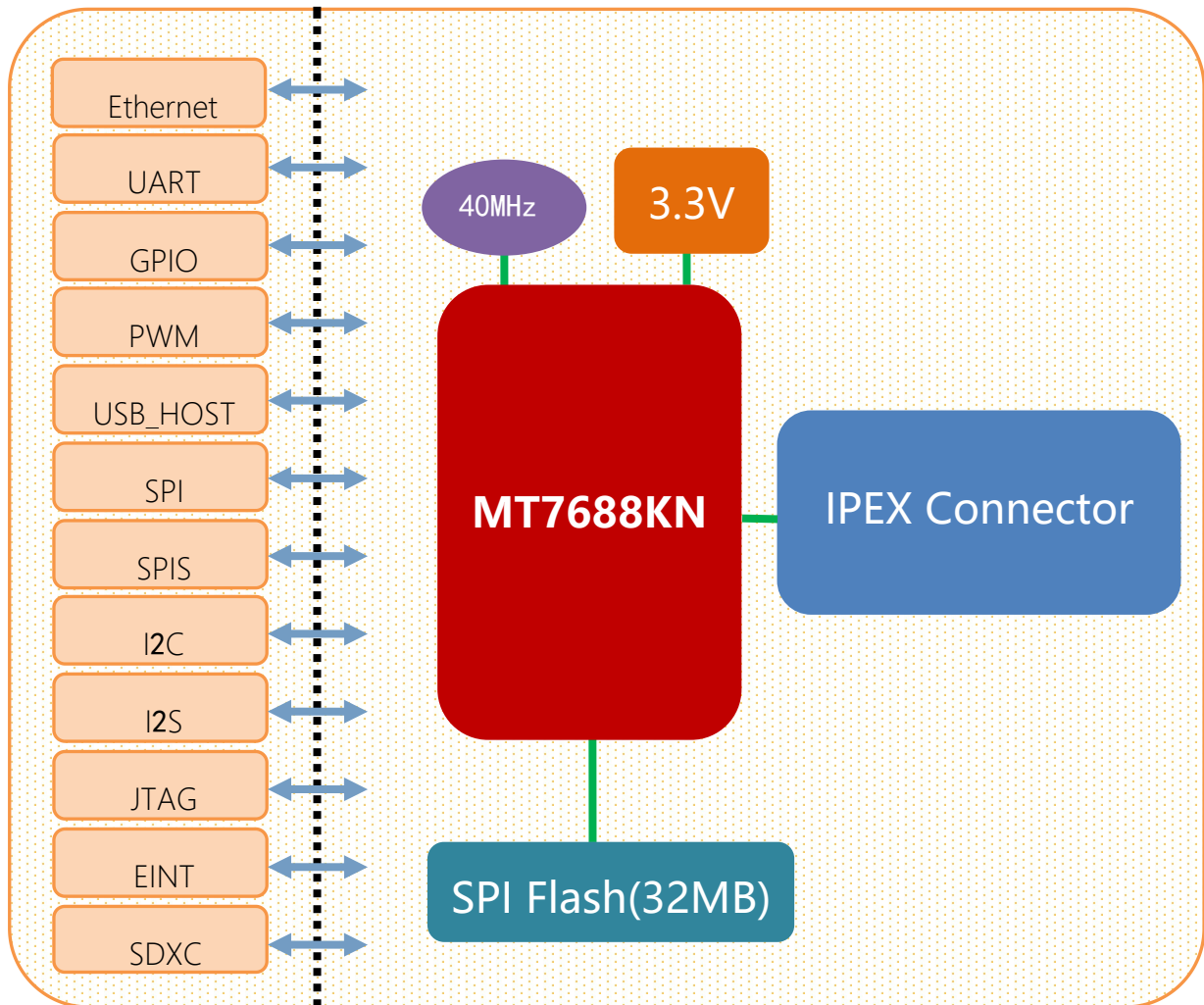
1. Brief Introduction

HLK-RM08S based on MT7688KN is a low cost and low power consumption IOT module developed by Hi-Link. The module has rich interfaces and powerful processor and could be widely used in smart devices and cloud service applications.

1.1. Basic parameters

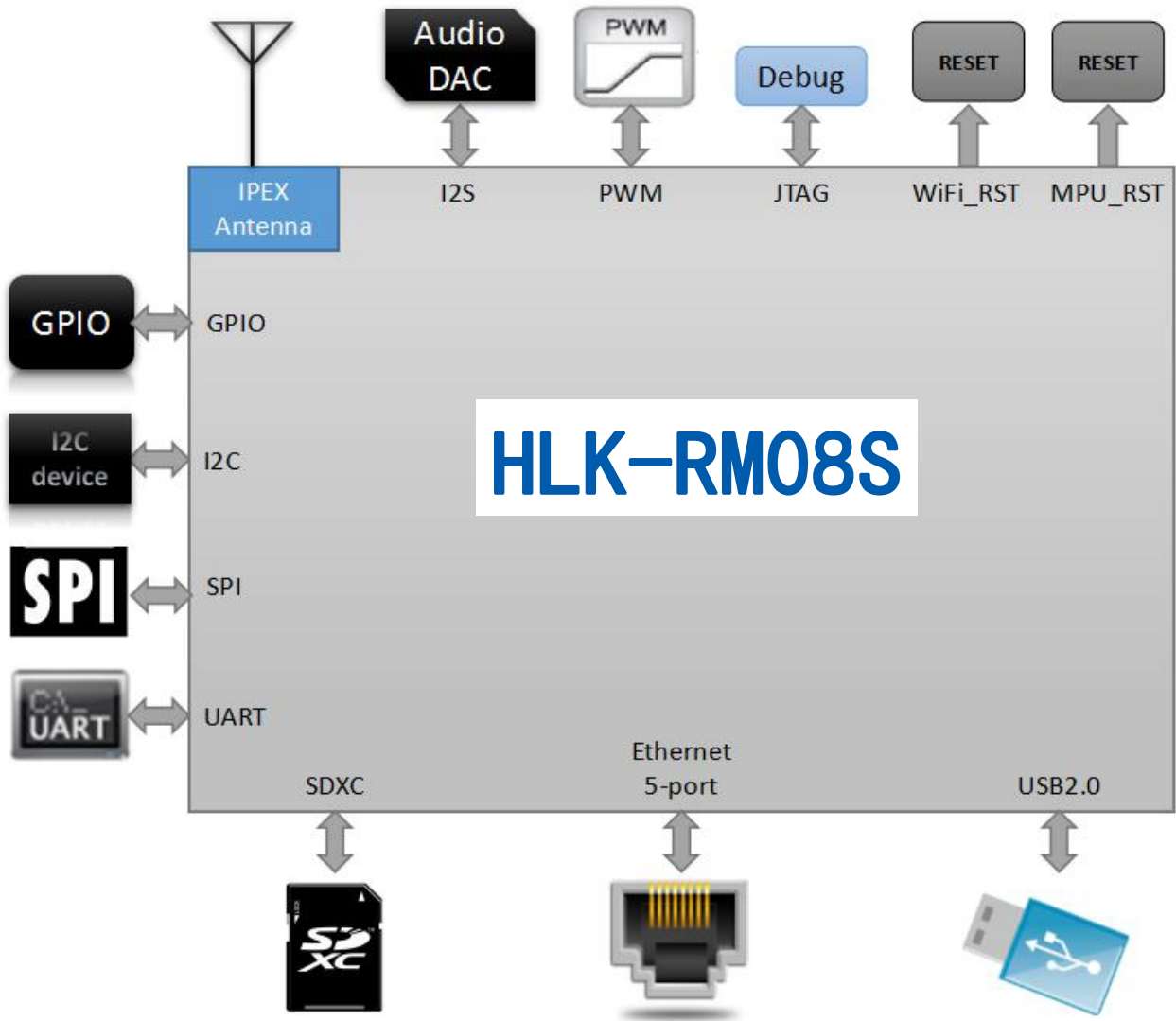
- High data processing ability, MCU frequency 580MHz
- 150M Mbps
- Support 802.11b/g/n mode
- 20/40 channel bandwidth
- Support 802.11v
- Support AP, STA and AP, STA mixed
- Fifth 10/100M adaptive com port
- One USB2.0 host interface
- Multiple interfaces SPI/SD-XC/eMMC
- Rich peripheral interfaces, SPI, I2C, I2S, PCM, UART, JTAG, GPIO
- Widely used in IOT
- Inbuilt powerful PMU
- Support 16 Multiple BSSID
- Support multiple encryption WEP64/128, TKIP, AES, WPA, WPA2, WAPI
- Support QoS, WMM, WMM-PS

2. Block diagram



HLK-RM08S Block Diagram

2.1. Typical application



HLK-RM08S typical peripheral interfaces diagram

2.2. Specification

Item	Parameter
Model	HLK-RM08S
Main Chip	MT7688KN
I-Cache, D-Cache	64KB,32KB
Kernel	MIPS24KEc
Main frequency	580MHz
RAM	64Mb
Flash	32Mb
RF	1T1R 802.11n 2.4GHz
USB2.0	1
UART	2
Temperature	Environmental temperature: -40℃~85℃
Humidity	working: 10~95% (noncondensing) Storage: 5~95% (noncondensing)
Size	17.4mm×25.8mm×2.8mm

3. Electrical characteristics

3.1. Input voltage

Name	Function	Min voltage (V)	Typical voltage (V)	Max Voltage (V)
VBAT	Supply voltage	3.2	3.3	3.4
I/O	I/O Voltage	3.2	3.3	3.4

3.2. RF Characteristics

3.2.1. 802.11b 11M

802.11b Transmit (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Tx Power Level	DQPSK	18	20	22	dBm
Frequency Tolerance		-15	0	15	ppm
Spectral Mask	11MHz→22MHz		40		dBr
	>22MHz		53		dBr
Modulation Accuracy	All Data Rate		15		%
802.11b Receiver (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Min. Input	11Mbps PER<8%	-91.5	-89.5	-87.5	dBm

3.2.2. 802.11g 54M

802.11g Transmit (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Tx Power Level	OFDM	15	17	19	dBm
Frequency Tolerance		-15	0	15	ppm
Modulation Accuracy	All Data Rate		-31	-28	%
802.11g Receiver (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Min. Input	54Mbps PER<10%	-78.0	-76.0	-74.0	dBm

3.2.3. 802.11n MCS7 (HT20)

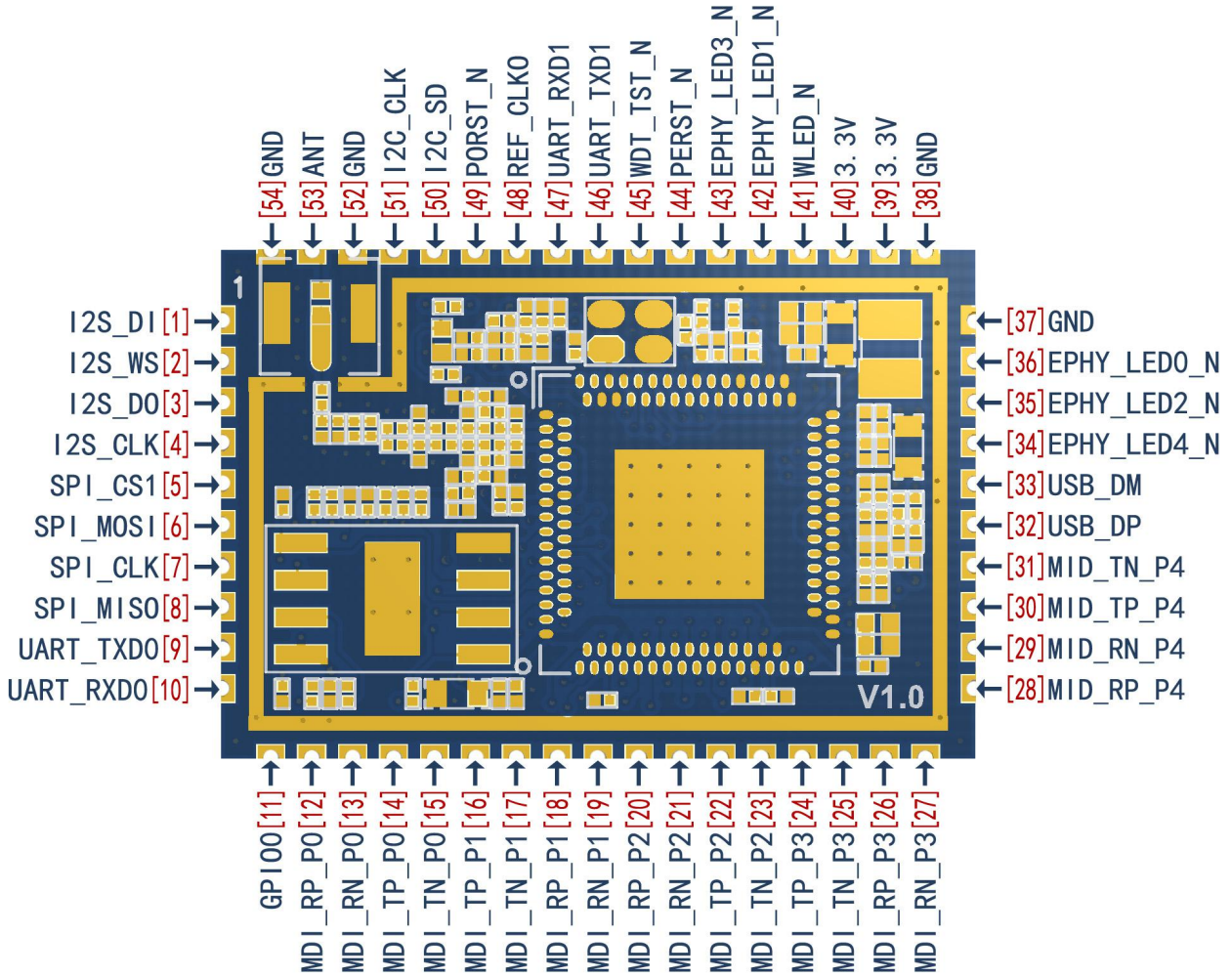
802.11n_HT20 Transmit (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Tx Power Level	OFDM	15	17	19	dBm
Frequency Tolerance		-15	0	15	ppm
Modulation Accuracy	All Data Rate		-31	-28	dB
802.11n_HT20 Receiver (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Min. Input	MCS7 PER<10%	-76.5	-74.5	-72.5	dBm

3.2.4. 802.11n MCS7 (HT40)

802.11n_HT40 Transmit (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Tx Power Level	OFDM	15.0	17.0	19.0	dBm
Frequency Tolerance		-15	0	15	ppm
Modulation Accuracy	All Data Rate		-31	-28	dB
802.11n_HT40 Receiver (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Min. Input	MCS7 PER<10%	-76.5	-74.5	-72.5	DBM

4. PINS DEFINITION

4.1. Pins definition diagram



HLK-RM08S Default pins definition diagram

4.2. Default pins definition

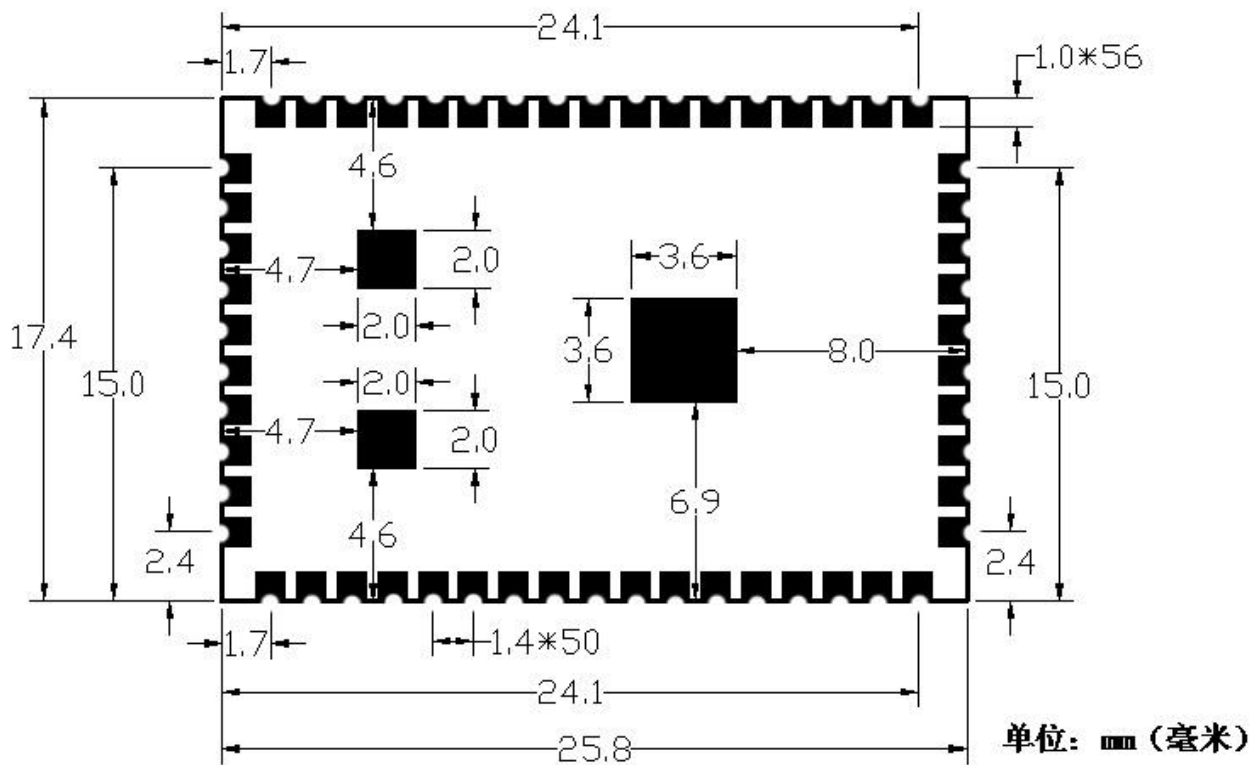
Pin	Name (Function 1)	Function 2	Function 3	Function 4	GPIO	Note
1	I2S_DI	PCMDRX			GPIO0	
2	I2S_WS	PCMLCK			GPIO2	
3	I2S_DO	PCMDTX			GPIO1	
4	I2S_CLK	PCMFS			GPIO3	
5	SPI_CS1			REF_CLKO	GPIO6	
6	SPI_MOSI				GPIO8	
7	SPI_CLK				GPIO7	
8	SPI_MISO				GPIO9	
9	UART_TXD0				GPIO12	Default is serial port TR
10	UART_RXD0				GPIO13	Default is serial port TR
11	GPIO0		REF_CLKO	PERST_N	GPIO11	
12	MDI_RP_P0				GPIO24	
13	MDI_RN_P0				GPIO23	
14	MDI_TP_P0				GPIO22	
15	MDI_TN_P0				GPIO21	
16	MDI_TP_P1	SPIS_CS		PWM_CH0	GPIO14	
17	MDI_TN_P1	SPIS_CLK		PWM_CH1	GPIO15	
18	MDI_RP_P1	SPIS_MISO		UART_TXD2	GPIO16	
19	MDI_RN_P1	SPI_MOSI		UART_RXD2	GPIO17	
20	MDI_RP_P2		eMMC_D7	PWM_CH0	GPIO18	
21	MDI_RN_P2		eMMC_D6	PWM_CH1	GPIO19	
22	MDI_TP_P2	UART_TXD2	eMMC_D5	PWM_CH2	GPIO20	
23	MDI_TN_P2	UART_RXD2	eMMC_D4	PWM_CH3	GPIO21	
24	MDI_TP_P3	SD_WP	eMMC_WP		GPIO22	
25	MDI_TN_P3	SD_CD	eMMC_CD		GPIO23	
26	MDI_RP_P3	SD_D1	eMMC_D1		GPIO24	

27	MDI_RN_P3	SD_D0	eMMC_D0		GPI025		
28	MDI_RP_P4	SD_CLK	eMMC_CLK		GPI026		
29	MDI_RN_P4	SD_CMD	eMMC_CMD		GPI028		
30	MDI_TP_P4	SD_D3	eMMC_D3		GPI029		
31	MDI_TN_P4	SD_D2	eMMC_D2		GPI027		
32	USB_DP					Default not available	
33	USB_DM					Default not available	
34	EPHY_LED4_N	JTAG_RST_N			GPI030	Com 4 status led	
35	EPHY_LED2	JTAG_TMS			GPI032	Com 2 status led	
36	EPHY_LED0	JTAG_TDO			GPI034	Com 0 status led	
37	GND						
38	GND						
39	3.3V					Suggested external power supply current \geq 500mA	
40	3.3V						
41	WLED_N				GPI035	WiFi status LED	
42	EPHY_LED1	JTAG_TDI			GPI033	Com 1 status LED	
43	EPHY_LED3	JTAG_CLK			GPI031	Com 3 status LED	
44	PORST_N					WIFI reset	
45	WDT_RST_N				GPI037	Watchdog timeout reset	
46	UART_TXD1			PWM_CH0	GPI045	Default is serial port TR	
47	UART_RXD1			PWM_CH1	GPI046	Default is serial port TR	
48	REF_CLK0				GPI038	Reference clock output	
49	PERST_N				GPI036	PCIe device reset	
50	I2C_SD				GPI05		
51	I2C_CLK				GPI04		
52	GND						
53	ANT						Default not connected
54	GND						

Notes:

- 1, All pins default 1
- 2, IO drive current is 4mA
- 3, All TTL is 3.3V

5. Dimensions



HLK-RM08S Drawing

Introductions:

- 1, The size of the module is length 1mm,width 1mm,space 1.4mm , depth 1.8mm.
 - 2, The thickness of the module is 1.8mm.
 - 3, The noted numbers in the picture is the actual size of module,do recommended pad extension around 1mm, internal heat shrink 0.2mm pad, internal thermal pad grounding once do encapsulation.
- Do when the package recommended pad extension around the 1mm, 3 internal heat shrink 0.2mm pad, internal thermal pad grounding.